

**AMENDMENTS TO THE CLAIMS:**

Please cancel claims 1-6 without prejudice or disclaimer. The listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1-6 (canceled).

Claim 7 (original): A patterning method comprising the steps of:  
coating a liquid, which reacts with an ultraviolet ray to deposit metal, on a substrate; and  
forming a metal film pattern by irradiating the ultraviolet ray onto the liquid while coating the liquid on the substrate or after the liquid is coated, to deposit the metal on the substrate.

Claim 8 (original): A patterning method according to claim 7, wherein the liquid is a liquid in which a metal complex is dissolved in a solvent.

Claim 9 (original): A patterning method according to claim 8, wherein the metal complex is any one of gold complex, copper complex, palladium complex, and nickel complex.

Claim 10 (original): A patterning method according to claim 8, wherein the metal complex includes gold cyanide.

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Claim 11 (original): A patterning method according to claim 7, wherein the step of forming the metal film pattern is executed in a state that the substrate is heated.

Claim 12 (original): A patterning method according to claim 7, wherein a film thickness of the metal film pattern is controlled by adjusting a radiation dose of the ultraviolet ray in the step of forming the metal film pattern.

Claim 13 (original): A patterning method according to claim 7, wherein the step of coating the liquid on the substrate is executed by an ink jet method.